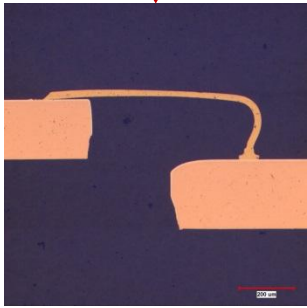
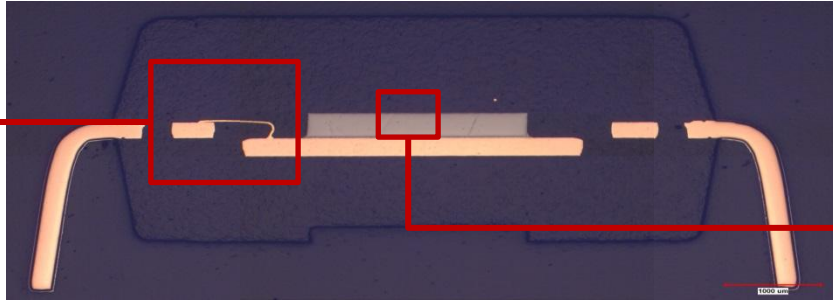


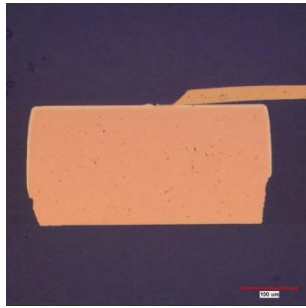
# Chip 단면 관찰

목적: Chip 단면 관찰을 위한 전처리

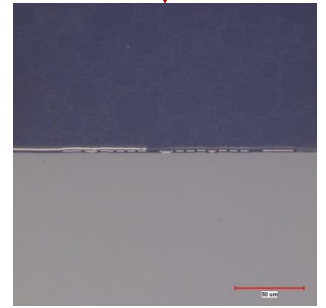
1. Bonding 접합부 단면 관찰
2. Die layer 단면 관찰



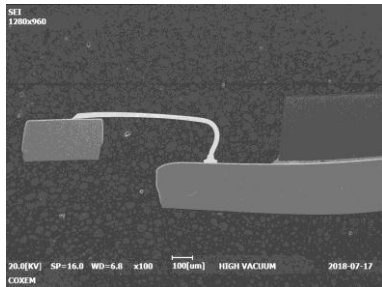
Bonding 접합부  
x100



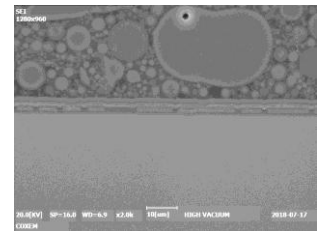
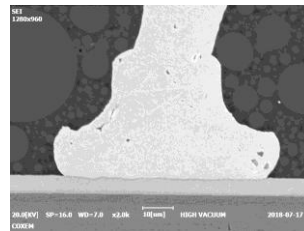
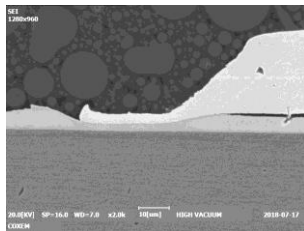
Bonding 접합부X200



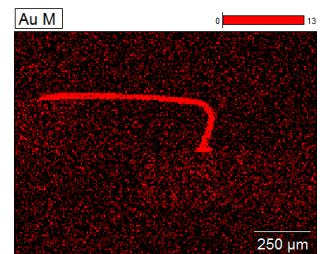
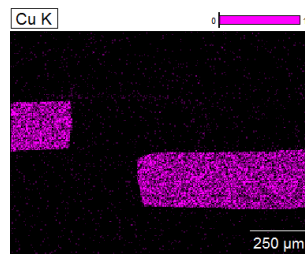
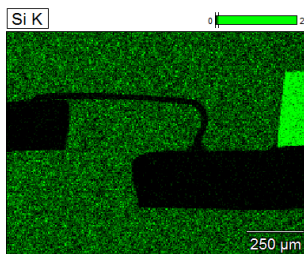
Die layer x500



SEM-x100



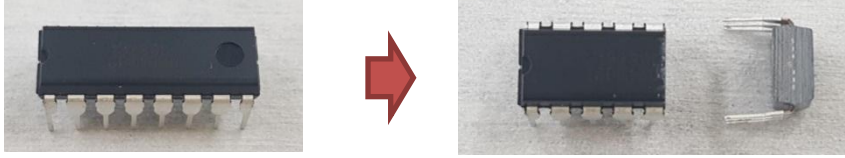
SEM-x2000



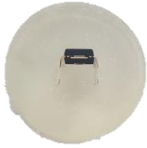
SEM - EDX Mapping

# 1. Cutting (WELL3500Premium)

- Diamond Wire Cutting



# 2. Cold Mounting (Pressure Chamber)



- Quick Set
- 32mm Mold



# 3. Grinding/Polishing(MetPrep3-PH3)

Step	Grinding			Polishing	
	1	2	3	4	5
<b>Abrasive</b>	600Grit (P-1200)	800 Grit (P-2400)	1200Grit (P-4000)	3 μm	0.05 μm
<b>Type</b>	SiC	SiC	SiC	Diamond	FinalPrep
<b>Carrier</b>	Abrasive Disc	Abrasive Disc	Abrasive Disc	Suspension	Solution
<b>Item No.</b>	50-10030	50-10035	50-10040	90-30020	90-187775
<b>Polishing Cloth</b>	-	-	-	DiaMat	Red FinalC
<b>Item No.</b>	-	-	-	90-700-550	90-700-350
<b>Coolant</b>	Water	Water	Water	GreenLube	-
<b>Item No.</b>	-	-	-	90-209010	-
<b>Platen Speed(RPM) / Direction</b>	100 /Comp	100 /Comp	100 /Comp	100 / Contra	100 / Contra
<b>Sample Speed (RPM)</b>	90	90	90	90	90
<b>Force (lbF)</b>	3	4	4	3	3
<b>Time (min)</b>	Until Target	30"	1'00"	2'00"	1'30"

※ 당사의 시편전처리 기술지원센터를 방문하시면

저희 장비를 직접 사용하실 수 있습니다.

※ 더 자세한 자료 및 견적서가 필요하신 분은  
아래의 연락처로 문의 주시면 친절히 대응해  
드리도록 하겠습니다. 감사합니다.



**CHINWOO TECH**

**SAMPLE PREP. CENTER**

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시편준비에 어려움을 겪고 계신 고객 분들을 지원 हे드리기 위해 시편제조기술센터(OPEN LAB.) 을 운영하고, 매일 정기교육을 실시하고 있사오니 언제든지 주저 마시고 활용해 주시기 바랍니다.